

Linear IC converter

CMOS

D/A Converter for Digital Tuning (8-channel, 8-bit, on-chip OP amp, low-voltage)

MB88347L

■ DESCRIPTION

The MB88347L incorporates eight 8-bit D/A converter modules. This device operates at low supply voltage in the performance guarantee range from 2.7 to 3.6 V. It also contains an output amplifier, allowing driving at large current.

Since the MB88347L inputs data in serial mode, it requires only three control lines for data input and two or more MB88347L units can be cascaded.

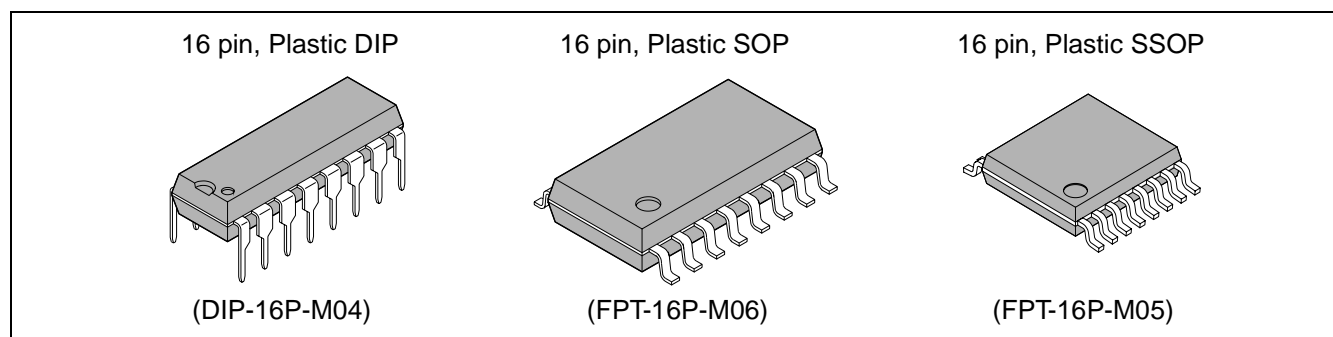
The MB88347L is function and pin compatible with the MB88347 (5-volt supply voltage model). The MB88347L can therefore easily replace the MB88347 in a system, thereby reducing the system's voltage requirement.

The MB88347L is the best replacement for electronic variable resistors or screwdriver control resistors.

■ FEATURES

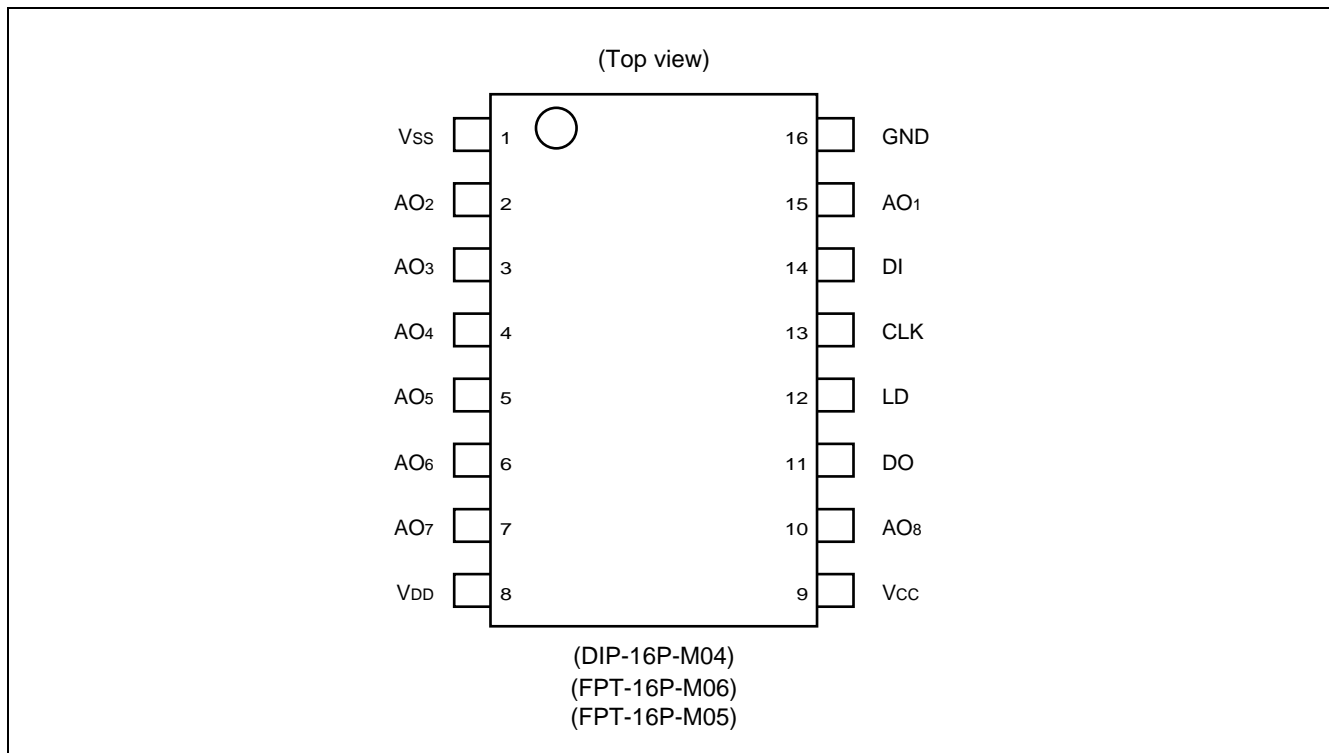
- Ultra-low power consumption (0.5 mW/ch: typical)
- Low voltage operation ($V_{CC} = 2.7$ to 3.6 V)
- Ultra-compact space-saving package (SSOP-16)
- Contains 8-channel R-2R type 8-bit D/A converter
- On-chip analog output amps (sink current max. 1.0 mA, source current max. 1.0 mA)
- Analog output range from 0 V to V_{CC}
- Two separate power supply/ground lines for MCU interface block/operational amplifier output buffer block and D/A converter block
- Serial data input, maximum operating speed 2.5 MHz
- CMOS process
- Package lineup includes DIP 16-pin, SOP 16-pin, SSOP 16-pin

■ PACKAGES



MB88347L

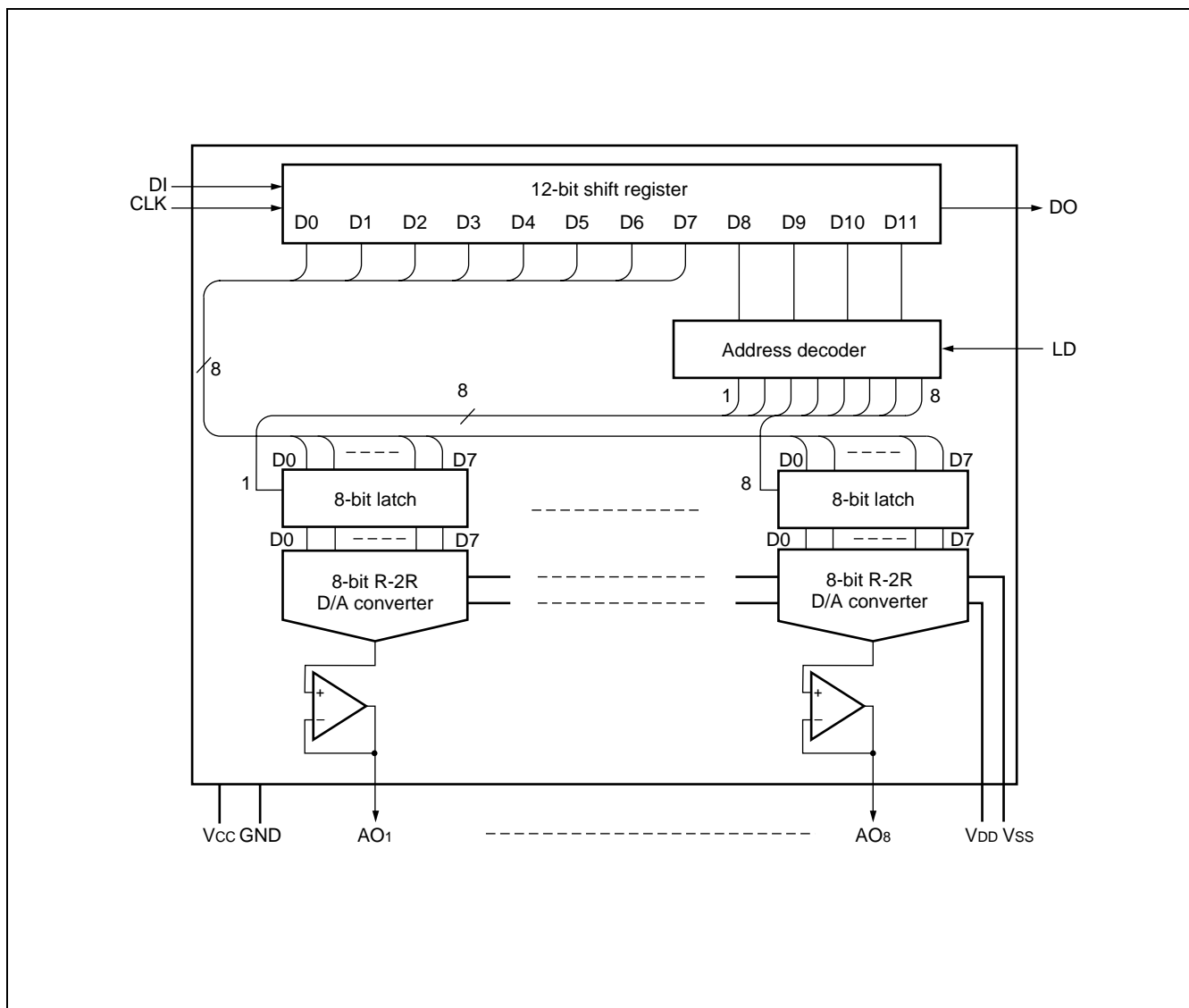
■ PIN ASSIGNMENT



■ PIN DESCRIPTION

Pin No.	Pin name	I/O	Functions
14	DI	I	Serial data input pin. This pin inputs serial data with a data length of 12 bits. (Do not leave the pin floating.)
11	DO	O	This pin outputs the MSB data in the 12-bit shift register at the CLK falling edge.
13	CLK	I	Shift clock input pin. The input signal from the DI pin enters the 12-bit shift register at the rising edge of the shift clock pulse. (Do not leave this pin floating.)
12	LD	I	When the LD pin inputs the High-level signal, shift register value is loaded to the decoder and the D/A output register. (Do not leave this pin floating. When data is not transferred, fix the pin to the "Low" level.)
15 2 3 4 5 6 7 10	AO1 AO2 AO3 AO4 AO5 AO6 AO7 AO8	O	8-bit D/A output with op amp.
9	VCC	—	MCU interface and OP amp power-supply pin.
16	GND	—	MCU interface and OP amp GND pin.
8	VDD	—	D/A converter reference power (High) input pin.
1	VSS	—	D/A converter reference power (Low) input pin.

■ BLOCK DIAGRAM



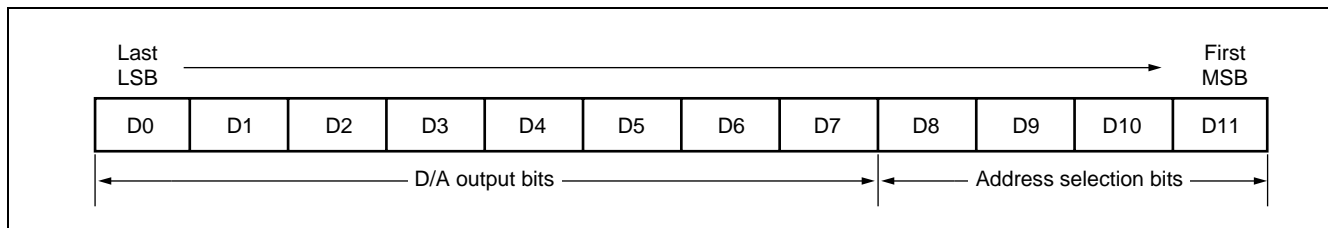
MB88347L

■ DATA CONFIGURATION

The MB88347L has a 12-bit shift register for chip control.

The 12-bit shift register must be used to set up data in the configuration shown below.

The data configuration has a total of 12 bits, for address selection and eight for D/A data output.



• D/A converter control signals

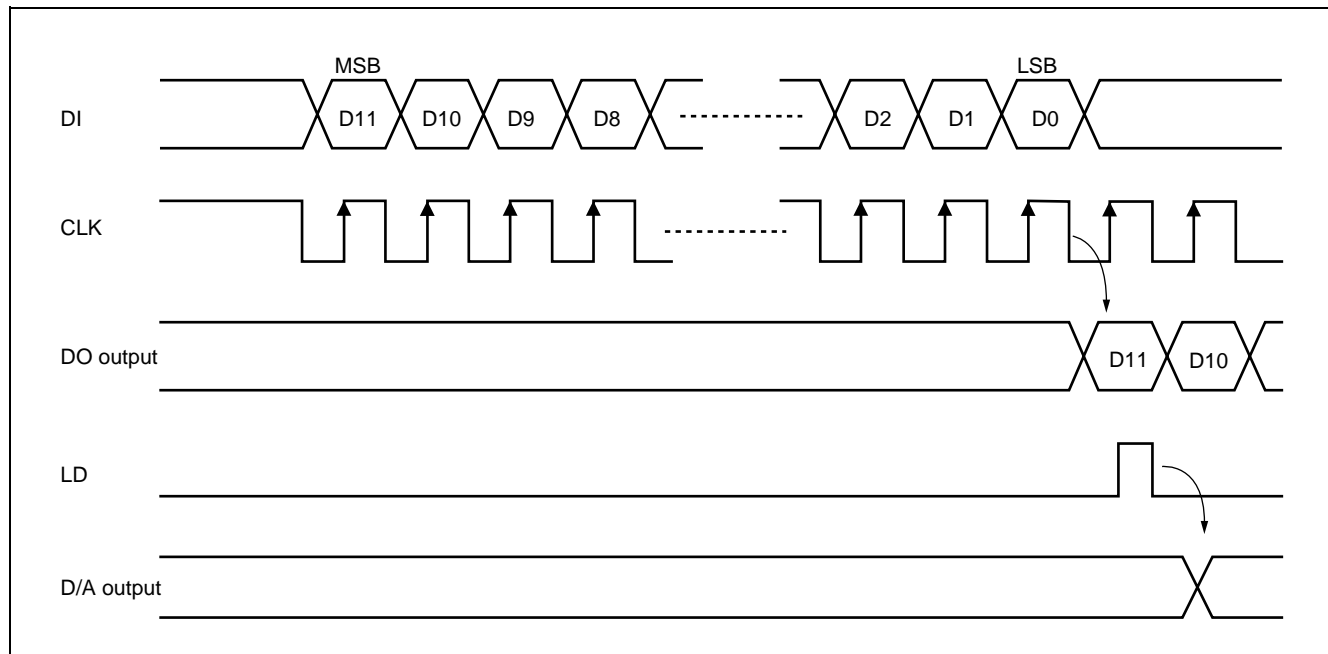
D0	D1	D2	D3	D4	D5	D6	D7	D/A data output
0	0	0	0	0	0	0	0	$\cong V_{SS}$
1	0	0	0	0	0	0	0	$\cong V_{LB} \times 1 + V_{SS}$
0	1	0	0	0	0	0	0	$\cong V_{LB} \times 2 + V_{SS}$
⋮	⋮	⋮	⋮	⋮	⋮	⋮	⋮	⋮
0	1	1	1	1	1	1	1	$\cong V_{LB} \times 254 + V_{SS}$
1	1	1	1	1	1	1	1	$\cong V_{LB} \times 255 + V_{SS}$

Note: $V_{LB} = (V_{DD} - V_{SS})/256$

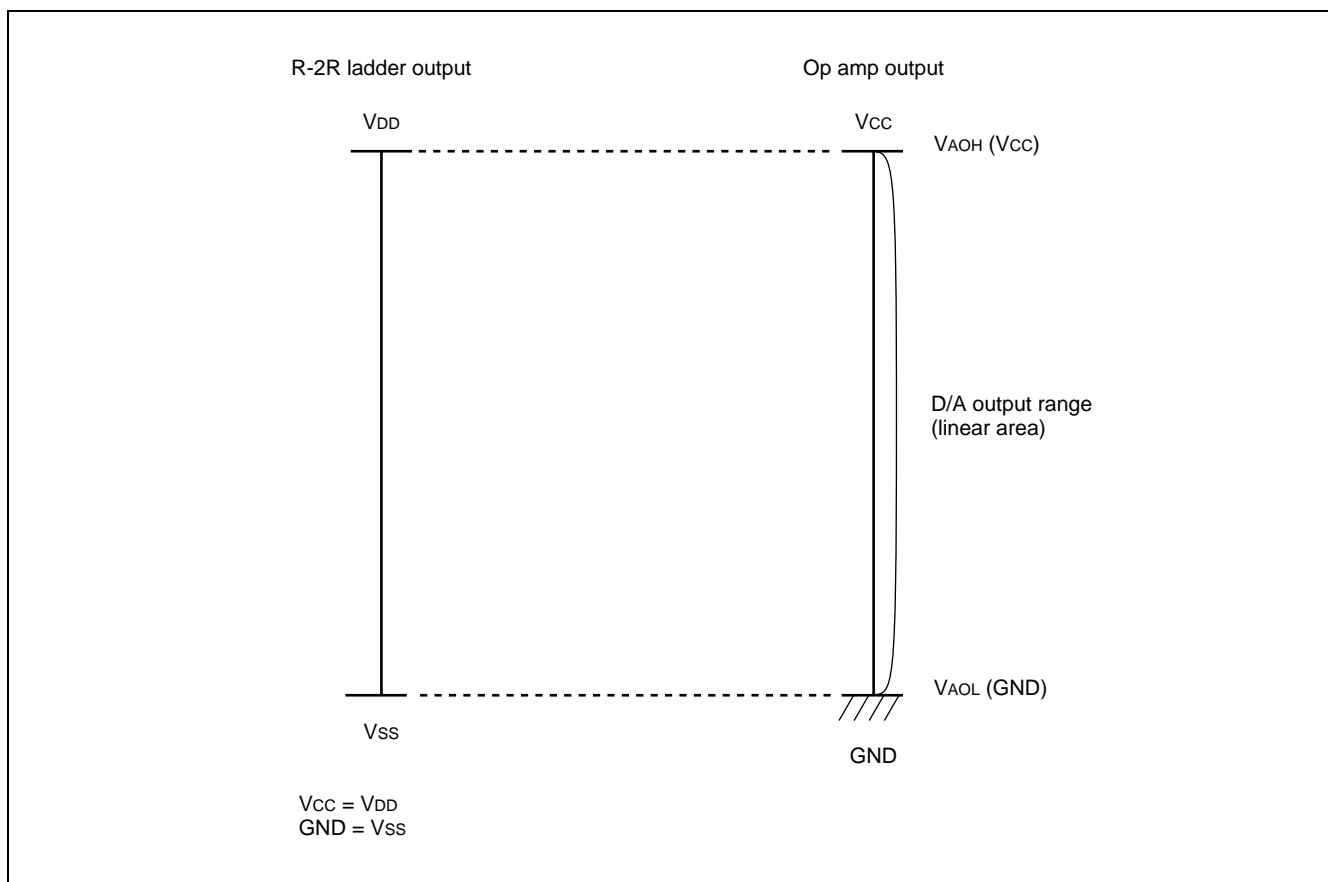
• Address selection signals

D8	D9	D10	D11	Address selection
0	0	0	0	Don't Care
0	0	0	1	AO ₁ Selection
0	0	1	0	AO ₂ Selection
0	0	1	1	AO ₃ Selection
0	1	0	0	AO ₄ Selection
0	1	0	1	AO ₅ Selection
0	1	1	0	AO ₆ Selection
0	1	1	1	AO ₇ Selection
1	0	0	0	AO ₈ Selection
1	0	0	1	Don't Care
1	0	1	0	Don't Care
1	0	1	1	Don't Care
1	1	0	0	Don't Care
1	1	0	1	Don't Care
1	1	1	0	Don't Care
1	1	1	1	Don't Care

■ DATA SETTING TIMING CHART



■ ANALOG OUTPUT VOLTAGE RANGE



■ ABSOLUTE MAXIMUM RATINGS

Parameter	Symbol	Conditions	Rating		Unit
			Min.	Max.	
Supply voltage	V _{CC}	Based on GND Ta = +25°C	−0.3	5.0	V
	V _{DD}		−0.3*	5.0*	V
Input voltage	V _{IN}		−0.3	V _{CC} + 0.3	V
Output voltage	V _{OUT}		−0.3	V _{CC} + 0.3	V
Power consumption	P _D	—	—	250	mW
Operating temperature	Ta	—	−20	+85	°C
Storage temperature	Tstg	—	−55	+150	°C

* : V_{CC} ≥ V_{DD}

WARNING: Semiconductor devices can be permanently damaged by application of stress (voltage, current, temperature, etc.) in excess of absolute maximum ratings. Do not exceed these ratings.

■ RECOMMENDED OPERATING CONDITIONS

Parameter	Symbol	Conditions	Rating		Unit
			Min.	Max.	
Power supply voltage 1	V _{CC}	—	2.7	3.6	V
	GND	—	Typical: 0		V
Power supply voltage 2	V _{DD}	V _{DD} − V _{SS} ≥ 2.0 V	2.0	V _{CC}	V
	V _{SS}		GND	V _{CC} − 2.0	V
Analog output source current	I _{AL}	V _{CC} = 3.0 V	—	1.0	mA
Analog output sink current	I _{AH}	V _{CC} = 3.0 V	—	1.0	mA
Oscillation limit output capacity	C _{OL}	—	—	1.0	μF
Digital data value range	—	—	#00	#FF	—
Operating temperature	Ta	—	−20	+85	°C

WARNING: The recommended operating conditions are required in order to ensure the normal operation of the semiconductor device. All of the device's electrical characteristics are warranted when the device is operated within these ranges.

Always use semiconductor devices within their recommended operating condition ranges. Operation outside these ranges may adversely affect reliability and could result in device failure.

No warranty is made with respect to uses, operating conditions, or combinations not represented on the data sheet. Users considering application outside the listed conditions are advised to contact their representatives beforehand.

■ ELECTRICAL CHARACTERISTICS

1. DC Characteristics

(1) Digital block

(V_{DD} , $V_{CC} = 2.7 \text{ V to } 3.6 \text{ V}$ ($V_{CC} \geq V_{DD}$), GND, $V_{SS} = 0 \text{ V}$, $T_a = -20^\circ\text{C to } +85^\circ\text{C}$)

Parameter	Symbol	Pin name	Conditions	Value			Unit
				Min.	Typ.	Max.	
Power supply voltage	V_{CC}	V_{CC}	—	2.7	3.0	3.6	V
Power supply current 1	I_{CC}		Operation at CLK = 1 MHz (with no load)	—	0.8	2.0	mA
Input leak current	I_{ILK}	CLK DI LD	$V_{IN} = 0 \text{ V to } V_{CC}$	-10	—	10	μA
L level input voltage	V_{IL}		—	—	—	$0.2 V_{CC}$	V
H level input voltage	V_{IH}		—	$0.8 V_{CC}$	—	—	V
L level output voltage	V_{OL}	DO	$I_{OL} = 2.5 \text{ mA}$	—	—	0.4	V
H level output voltage	V_{OH}		$I_{OH} = -400 \mu\text{A}$	$V_{CC} - 0.4$	—	—	V

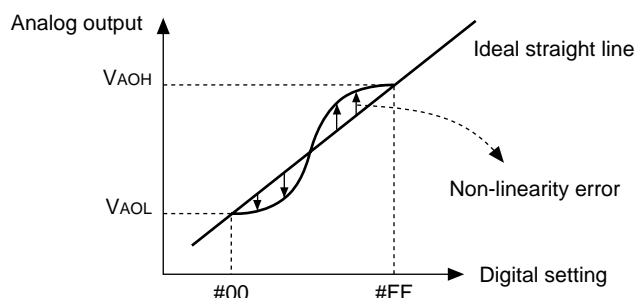
(2) Analog block (1)

(V_{DD} , $V_{CC} = 2.7 \text{ V to } 3.6 \text{ V}$ ($V_{CC} \geq V_{DD}$), GND, $V_{SS} = 0 \text{ V}$, $T_a = -20^\circ\text{C to } +85^\circ\text{C}$)

Parameter	Symbol	Pin name	Conditions	Value			Unit
				Min.	Typ.	Max.	
Power consumption	I_{DD}	V_{DD}	No load	—	0.6	1.0	mA
Analog voltage	V_{DD}	V_{DD}	$V_{DD} - V_{SS} \geq 2.0 \text{ V}$	2.0	—	V_{CC}	V
	V_{SS}	V_{SS}		GND	—	$V_{CC} - 2.0$	V
Resolution	Res	AO ₁ to AO ₈	—	—	8	—	bits
Monotonic increase	Rem		No load $V_{DD} \leq V_{CC} - 0.1 \text{ V}$ $V_{SS} \geq 0.1 \text{ V}$	—	8	—	bits
Non-linearity error*1	LE			-1.5	—	1.5	LSB
Differential linearity error*2	DLE			-1.0	—	1.0	LSB

*1: Deviation (error) in input/output curves with respect to an ideal straight line connecting output voltage at “00” and output voltage at “FF.”

*2: Deviation (error) in amplification with respect to theoretical increase in amplification per 1-bit increase in digital value.



Note: The value of V_{AOH} and V_{DD} , and the value of V_{AOL} and V_{SS} are not necessarily equivalent.

(3) Analog section (2)

(Ta = -20°C to +85°C)

Parameter	Symbol	Pin name	Conditions	Values			Unit
				Min.	Typ.	Max.	
Output minimum voltage 1	VAOL1	AO ₁ to AO ₈	V _{DD} = V _{CC} = 3.0 V V _{SS} = GND = 0.0 V I _{AL} = 0 μA Digital data = #00	V _{SS}	—	V _{SS} + 0.1	V
Output minimum voltage 2	VAOL2		V _{DD} = V _{CC} = 3.0 V V _{SS} = GND = 0.0 V I _{AL} = 500 μA Digital data = #00	V _{SS} - 0.2	V _{SS}	V _{SS} + 0.2	V
Output minimum voltage 3	VAOL3		V _{DD} = V _{CC} = 3.0 V V _{SS} = GND = 0.0 V I _{AH} = 500 μA Digital data = #00	V _{SS}	—	V _{SS} + 0.2	V
Output minimum voltage 4	VAOL4		V _{DD} = V _{CC} = 3.0 V V _{SS} = GND = 0.0 V I _{AL} = 1.0 mA Digital data = #00	V _{SS} - 0.3	V _{SS}	V _{SS} + 0.3	V
Output minimum voltage 5	VAOL5		V _{DD} = V _{CC} = 3.0 V V _{SS} = GND = 0.0 V I _{AH} = 1.0 mA Digital data = #00	V _{SS}	—	V _{SS} + 0.3	V
Output maximum voltage 1	VAOH1		V _{DD} = V _{CC} = 3.0 V V _{SS} = GND = 0.0 V I _{AL} = 0 μA Digital data = #FF	V _{DD} - 0.1	—	V _{DD}	V
Output maximum voltage 2	VAOH2		V _{DD} = V _{CC} = 3.0 V V _{SS} = GND = 0.0 V I _{AL} = 500 μA Digital data = #FF	V _{DD} - 0.2	—	V _{DD}	V
Output maximum voltage 3	VAOH3		V _{DD} = V _{CC} = 3.0 V V _{SS} = GND = 0.0 V I _{AH} = 500 μA Digital data = #FF	V _{DD} - 0.2	V _{DD}	V _{DD} + 0.2	V
Output maximum voltage 4	VAOH4		V _{DD} = V _{CC} = 3.0 V V _{SS} = GND = 0.0 V I _{AL} = 1.0 mA Digital data = #FF	V _{DD} - 0.3	—	V _{DD}	V
Output maximum voltage 5	VAOH5		V _{DD} = V _{CC} = 3.0 V V _{SS} = GND = 0.0 V I _{AH} = 1.0 mA Digital data = #FF	V _{DD} - 0.3	V _{DD}	V _{DD} + 0.3	V

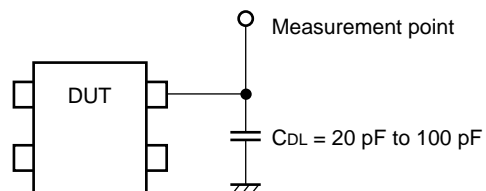
2. AC Characteristics

(V_{DD} , $V_{CC} = 2.7 \text{ V to } 3.6 \text{ V}$ ($V_{CC} \geq V_{DD}$), GND , $V_{SS} = 0 \text{ V}$, $T_a = -20^\circ\text{C to } +85^\circ\text{C}$)

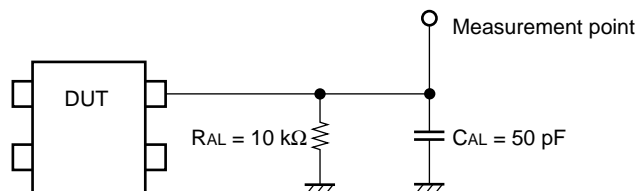
Parameter	Symbol	Conditions	Rating		Unit
			Min.	Max.	
Clock L level pulse width	t_{CKL}	—	200	—	ns
Clock H level pulse width	t_{CKH}	—	200	—	ns
Clock rise time Clock fall time	t_{Cr} t_{Cf}	—	—	200	ns
Data setup time	t_{DCH}	—	30	—	ns
Data hold time	t_{CHD}	—	60	—	ns
Load setup time	t_{CHL}	—	200	—	ns
Load hold time	t_{LDC}	—	100	—	ns
Load H level pulse width	t_{LDH}	—	100	—	ns
Data output delay time	t_{DO}	See “Load conditions (1).”	—	170	ns
D/A output settling time	t_{LDD}	See “Load conditions (2).”	—	200	μs

Load conditions

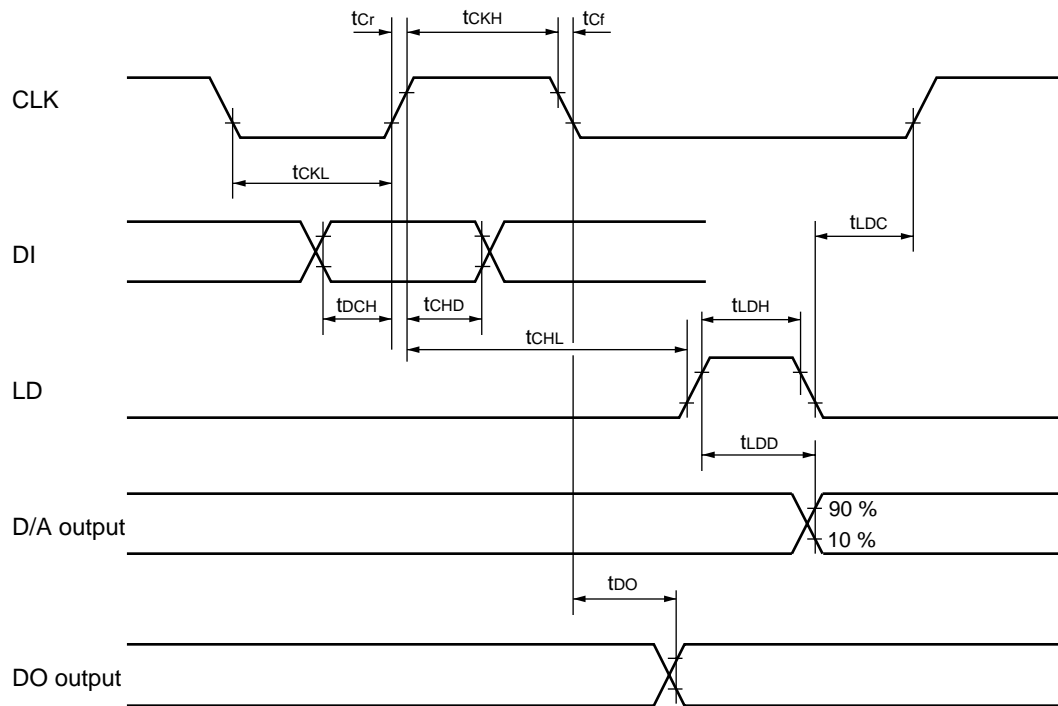
• Load conditions (1)



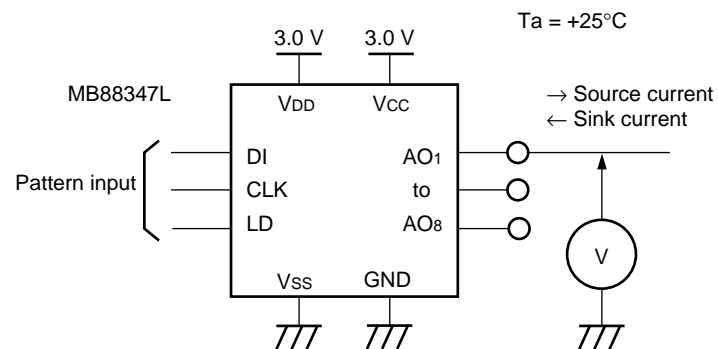
• Load conditions (2)



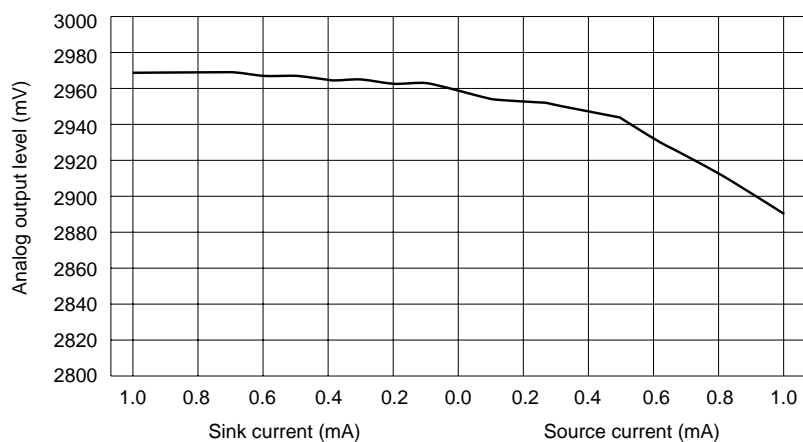
Input/output timing



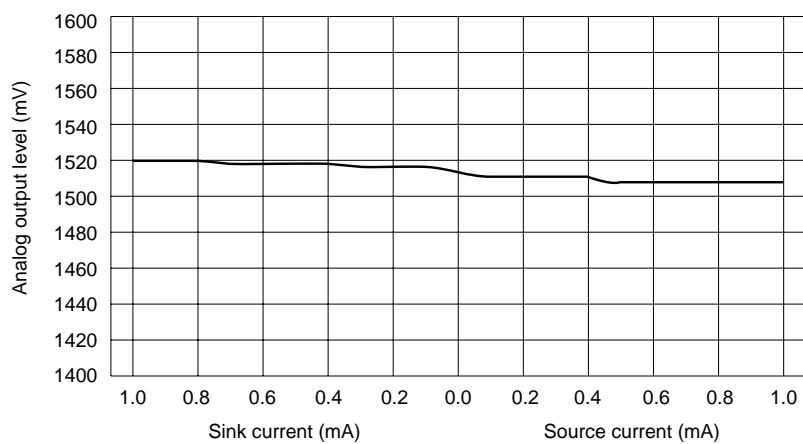
■ V_{AO} vs. I_{AO} CHARACTERISTICS: EXAMPLE



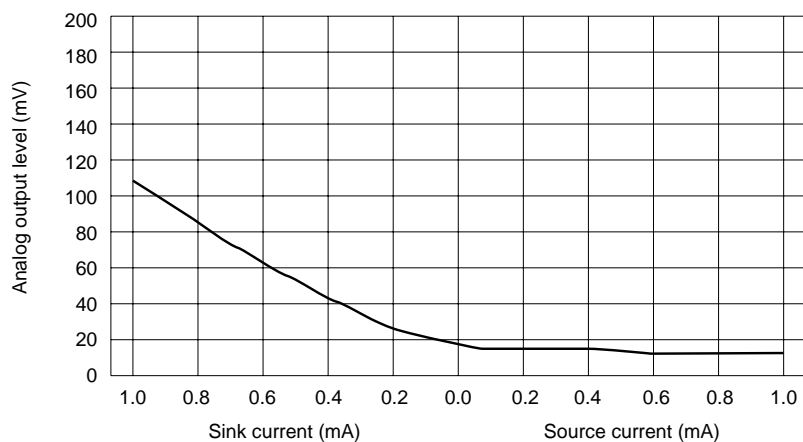
#FF setting



#80 setting



#00 setting



MB88347L

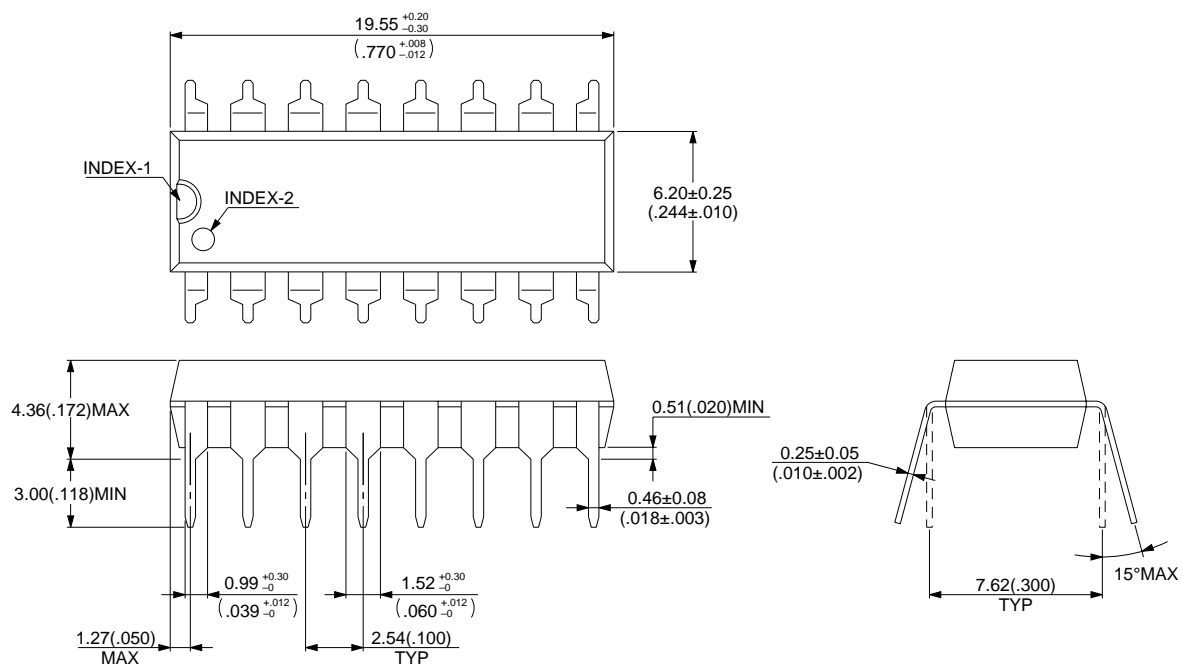
■ ORDERING INFORMATION

Part number	Package	Remarks
MB88347LP	16 pin, Plastic DIP (DIP-16P-M04)	
MB88347LPF	16 pin, Plastic SOP (FPT-16P-M06)	
MB88347LPFV	16 pin, Plastic SSOP (FPT-16P-M05)	

■ PACKAGE DIMENSIONS

16 pin, Plastic DIP

(DIP-16P-M04)



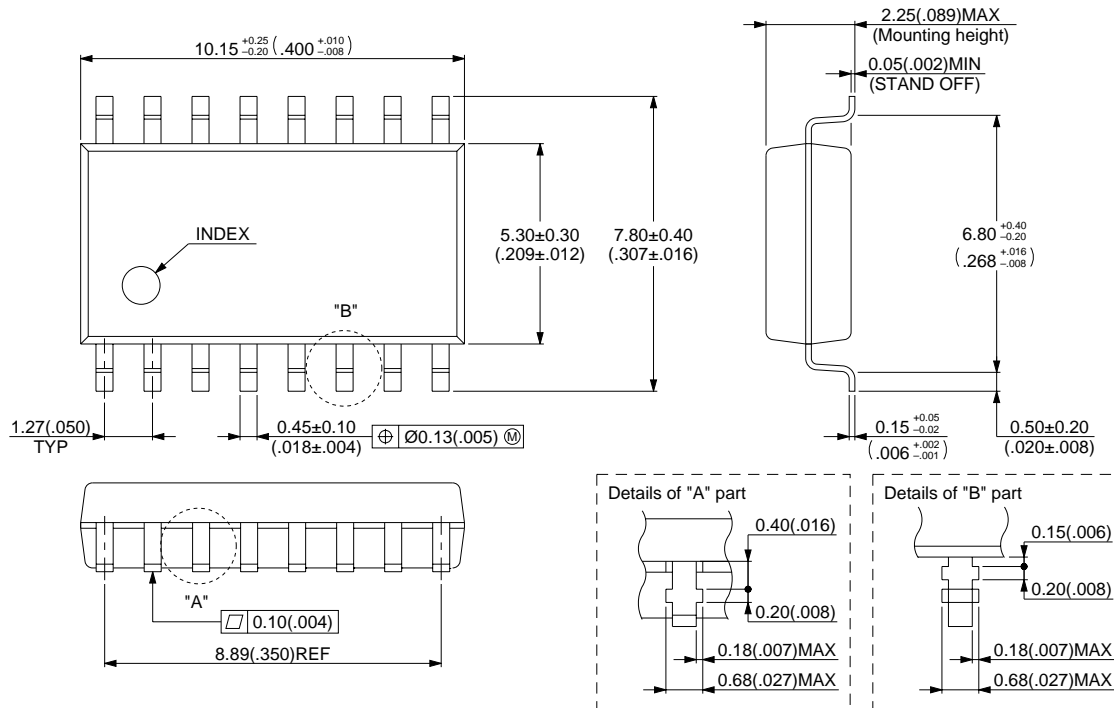
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Dimensions in mm (inches).

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MB88347L

16 pin, Plastic SOP
(FPT-16P-M06)



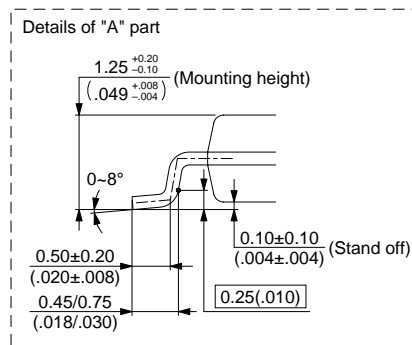
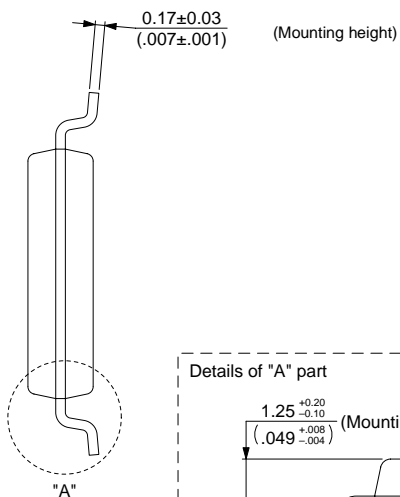
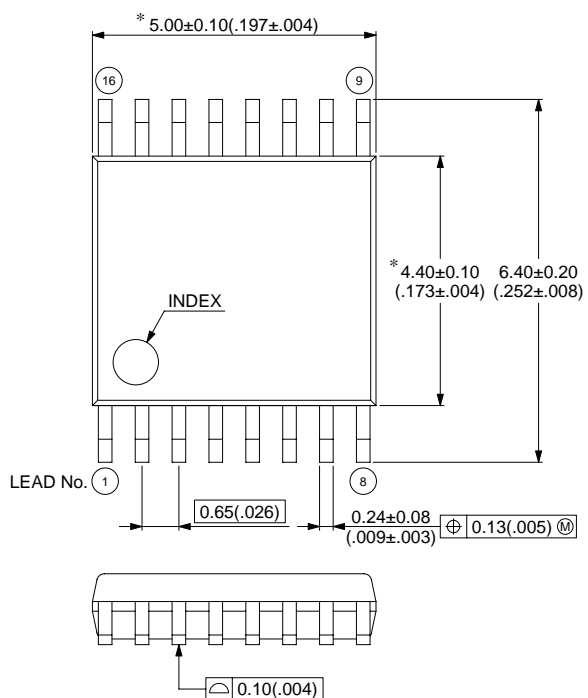
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Dimensions in mm (inches).

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16 pin, Plastic SSOP
(FPT-16P-M05)

Note 1) *: These dimensions do not include resin protrusion.
Note 2) Pins width and pins thickness include plating thickness.



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Dimensions in mm (inches).

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